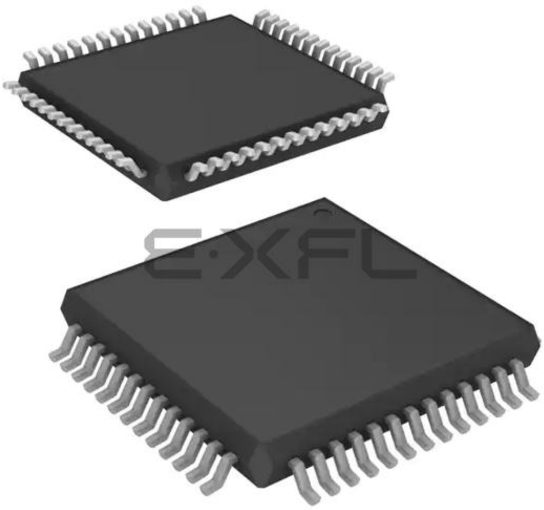

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Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
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Supplier Device Package	52-TQFP (10x10)
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2.3.2.5 Port J Registers

2.3.2.5.1 Port J I/O Register (PTJ)

Module Base + 0x0028

	7	6	5	4	3	2	1	0
R	PTJ7	PTJ6	0	0	0	0	0	0
W								
Reset	0	0	—	—	—	—	—	—

= Unimplemented or Reserved

Figure 2-32. Port J I/O Register (PTJ)

Read: Anytime.

Write: Anytime.

If the data direction bits of the associated I/O pins are set to 1, a read returns the value of the port register, otherwise the value at the pins is read.

2.3.2.5.2 Port J Input Register (PTIJ)

Module Base + 0x0029

	7	6	5	4	3	2	1	0
R	PTIJ7	PTIJ6	0	0	0	0	0	0
W								
Reset	0	0	—	—	—	—	—	—

= Unimplemented or Reserved

Figure 2-33. Port J Input Register (PTIJ)

Read: Anytime.

Write: Never, writes to this register have no effect.

This register always reads back the status of the associated pins. This can be used to detect overload or short circuit conditions on output pins.

2.3.2.5.3 Port J Data Direction Register (DDRJ)

Module Base + 0x002A

	7	6	5	4	3	2	1	0
R	DDRJ7	DDRJ6	0	0	0	0	0	0
W								
Reset	0	0	—	—	—	—	—	—

= Unimplemented or Reserved

Figure 2-34. Port J Data Direction Register (DDRJ)

Read: Anytime.

Write: Anytime.

Table 2-28. DDRJ Field Descriptions

Field	Description
7–6 DDRJ[7:6]	**Data Direction Port J** — This register configures port pins J[7:6] as either input or output. DDRJ[7:6] — Data Direction Port J 0 Associated pin is configured as input. 1 Associated pin is configured as output. **Note:** Due to internal synchronization circuits, it can take up to 2 bus cycles until the correct value is read on PTJ or PTIJ registers, when changing the DDRJ register.

2.3.2.5.4 Port J Reduced Drive Register (RDRJ)

Module Base + 0x002B

	7	6	5	4	3	2	1	0
R	RDRJ7	RDRJ6	0	0	0	0	0	0
W								
Reset	0	0	—	—	—	—	—	—

= Unimplemented or Reserved

Figure 2-35. Port J Reduced Drive Register (RDRJ)

Read: Anytime.

Write: Anytime.

Table 2-29. RDRJ Field Descriptions

Field	Description
7–6 RDRJ[7:6]	**Reduced Drive Port J** — This register configures the drive strength of each port J output pin as either full or reduced. If the port is used as input this bit is ignored. 0 Full drive strength at output. 1 Associated pin drives at about 1/3 of the full drive strength.

2.3.2.6 Port AD Registers

2.3.2.6.1 Port AD I/O Register (PTAD)

Module Base + 0x0030

	7	6	5	4	3	2	1	0
R/W	PTAD7	PTAD6	PTAD5	PTAD4	PTAD3	PTAD2	PTAD1	PTAD0
Reset	0	0	0	0	0	0	0	0

Figure 2-40. Port AD I/O Register (PTAD)

Read: Anytime.

Write: Anytime.

If the data direction bits of the associated I/O pins are set to 1, a read returns the value of the port register, otherwise the value at the pins is read.

2.3.2.6.2 Port AD Input Register (PTIAD)

Module Base + 0x0031

	7	6	5	4	3	2	1	0
R	PTIAD7	PTIAD6	PTIAD5	PTIAD4	PTIAD3	PTIAD2	PTIAD1	PTIAD0
W								
Reset	—	—	—	—	—	—	—	—

= Unimplemented or Reserved

Figure 2-41. Port AD Input Register (PTIAD)

Read: Anytime.

Write: Never, writes to this register have no effect.

This register always reads back the status of the associated pins. This can be used to detect overload or short circuit conditions on output pins.

NOTE

To ensure that you read the value present on the PORTE pins, always wait at least one cycle after writing to the DDRE register before reading from the PORTE register.

4.3.2.7 Data Direction Register E (DDRE)

Module Base + 0x0009
Starting address location affected by INITRG register setting.

	7	6	5	4	3	2	1	0
R	Bit 7	6	5	4	3	Bit 2	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 4-11. Data Direction Register E (DDRE)

Read: Anytime when register is in the map

Write: Anytime when register is in the map

Data direction register E is associated with port E. For bits in port E that are configured as general-purpose I/O lines, DDRE determines the primary direction of each of these pins. A 1 causes the associated bit to be an output and a 0 causes the associated bit to be an input. Port E bit 1 (associated with $\overline{\text{IRQ}}$) and bit 0 (associated with $\overline{\text{XIRQ}}$) cannot be configured as outputs. Port E, bits 1 and 0, can be read regardless of whether the alternate interrupt function is enabled. The value in a DDR bit also affects the source of data for reads of the corresponding PORTE register. If the DDR bit is 0 (input) the buffered pin input state is read. If the DDR bit is 1 (output) the associated port data register bit state is read.

This register is not in the on-chip memory map in expanded and special peripheral modes. Therefore, these accesses will be echoed externally. Also, it is not in the map in expanded modes while the EME control bit is set.

Table 4-5. DDRE Field Descriptions

Field	Description
7:2 DDRE	**Data Direction Port E** 0 Configure the corresponding I/O pin as an input 1 Configure the corresponding I/O pin as an output **Note:** It is unwise to write PORTE and DDRE as a word access. If you are changing port E pins from inputs to outputs, the data may have extra transitions during the write. It is best to initialize PORTE before enabling as outputs.

Chapter 6
Background Debug Module (BDMV4) Block Description

6.1 Introduction

This section describes the functionality of the background debug module (BDM) sub-block of the HCS12 core platform.

A block diagram of the BDM is shown in Figure 6-1.

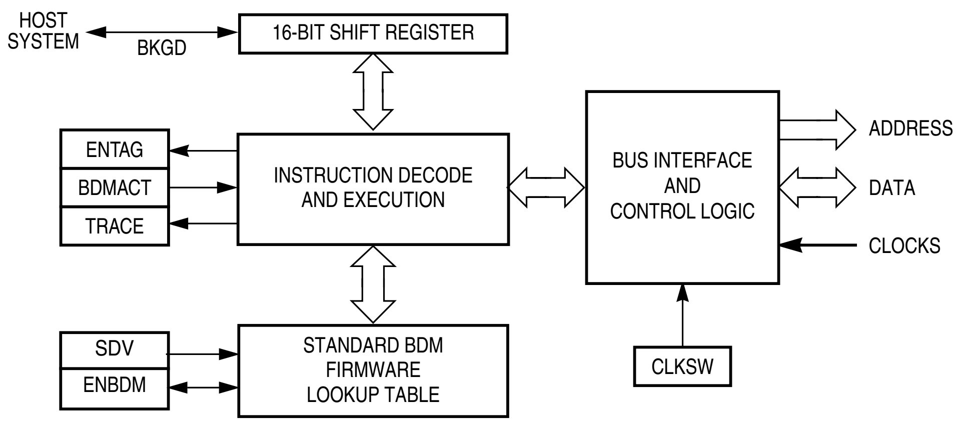

Figure 6-1. BDM Block Diagram

The background debug module (BDM) sub-block is a single-wire, background debug system implemented in on-chip hardware for minimal CPU intervention. All interfacing with the BDM is done via the BKGD pin.

BDMV4 has enhanced capability for maintaining synchronization between the target and host while allowing more flexibility in clock rates. This includes a sync signal to show the clock rate and a handshake signal to indicate when an operation is complete. The system is backwards compatible with older external interfaces.

6.1.1 Features

- Single-wire communication with host development system
- BDMV4 (and BDM2): Enhanced capability for allowing more flexibility in clock rates
- BDMV4: SYNC command to determine communication rate
- BDMV4: GO_UNTIL command
- BDMV4: Hardware handshake protocol to increase the performance of the serial communication
- Active out of reset in special single-chip mode

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
Left Justified Result Data										
0x0010	ATDDR0H	R	BIT 9 MSB BIT 7 MSB	BIT 8 BIT 6	BIT 7 BIT 5	BIT 6 BIT 4	BIT 5 BIT 3	BIT 4 BIT 2	BIT 3 BIT 1	BIT 2 BIT 0
		W								
0x0011	ATDDR0L	R	BIT 1 u	BIT 0 u	0 0	0 0	0 0	0 0	0 0	0 0
		W								
0x0012	ATDDR1H	R	BIT 9 MSB BIT 7 MSB	BIT 8 BIT 6	BIT 7 BIT 5	BIT 6 BIT 4	BIT 5 BIT 3	BIT 4 BIT 2	BIT 3 BIT 1	BIT 2 BIT 0
		W								
0x0013	ATDDR1L	R	BIT 1 u	BIT 0 u	0 0	0 0	0 0	0 0	0 0	0 0
		W								
0x0014	ATDDR2H	R	BIT 9 MSB BIT 7 MSB	BIT 8 BIT 6	BIT 7 BIT 5	BIT 6 BIT 4	BIT 5 BIT 3	BIT 4 BIT 2	BIT 3 BIT 1	BIT 2 BIT 0
		W								
0x0015	ATDDR2L	R	BIT 1 u	BIT 0 u	0 0	0 0	0 0	0 0	0 0	0 0
		W								
0x0016	ATDDR3H	R	BIT 9 MSB BIT 7 MSB	BIT 8 BIT 6	BIT 7 BIT 5	BIT 6 BIT 4	BIT 5 BIT 3	BIT 4 BIT 2	BIT 3 BIT 1	BIT 2 BIT 0
		W								
0x0017	ATDDR3L	R	BIT 1 u	BIT 0 u	0 0	0 0	0 0	0 0	0 0	0 0
		W								
0x0018	ATDDR4H	R	BIT 9 MSB BIT 7 MSB	BIT 8 BIT 6	BIT 7 BIT 5	BIT 6 BIT 4	BIT 5 BIT 3	BIT 4 BIT 2	BIT 3 BIT 1	BIT 2 BIT 0
		W								
0x0019	ATDDR4L	R	BIT 1 u	BIT 0 u	0 0	0 0	0 0	0 0	0 0	0 0
		W								
0x001A	ATDDR5H	R	BIT 9 MSB BIT 7 MSB	BIT 8 BIT 6	BIT 7 BIT 5	BIT 6 BIT 4	BIT 5 BIT 3	BIT 4 BIT 2	BIT 3 BIT 1	BIT 2 BIT 0
		W								
0x001B	ATDDR5L	R	BIT 1 u	BIT 0 u	0 0	0 0	0 0	0 0	0 0	0 0
		W								
0x001C	ATDDR6H	R	BIT 9 MSB BIT 7 MSB	BIT 8 BIT 6	BIT 7 BIT 5	BIT 6 BIT 4	BIT 5 BIT 3	BIT 4 BIT 2	BIT 3 BIT 1	BIT 2 BIT 0
		W								
0x001D	ATDDR6L	R	BIT 1 u	BIT 0 u	0 0	0 0	0 0	0 0	0 0	0 0
		W								

= Unimplemented or Reserved

Figure 8-2. ATD Register Summary (Sheet 2 of 4)

8.3.2.5 ATD Control Register 4 (ATDCTL4)

This register selects the conversion clock frequency, the length of the second phase of the sample time and the resolution of the A/D conversion (i.e.: 8-bits or 10-bits). Writes to this register will abort current conversion sequence but will not start a new sequence.

Module Base + 0x0004

	7	6	5	4	3	2	1	0
R W	SRES8	SMP1	SMP0	PRS4	PRS3	PRS2	PRS1	PRS0
Reset	0	0	0	0	0	1	0	1

Figure 8-7. ATD Control Register 4 (ATDCTL4)

Read: Anytime

Write: Anytime

Table 8-6. ATDCTL4 Field Descriptions

Field	Description
7 SRES8	**A/D Resolution Select** — This bit selects the resolution of A/D conversion results as either 8 or 10 bits. The A/D converter has an accuracy of 10 bits; however, if low resolution is required, the conversion can be speeded up by selecting 8-bit resolution. 0 10-bit resolution 1 8-bit resolution
6–5 SMP[1:0]	**Sample Time Select** — These two bits select the length of the second phase of the sample time in units of ATD conversion clock cycles. Note that the ATD conversion clock period is itself a function of the prescaler value (bits PRS4-0). The sample time consists of two phases. The first phase is two ATD conversion clock cycles long and transfers the sample quickly (via the buffer amplifier) onto the A/D machine's storage node. The second phase attaches the external analog signal directly to the storage node for final charging and high accuracy. Table 8-7 lists the lengths available for the second sample phase.
4–0 PRS[4:0}	**ATD Clock Prescaler** — These 5 bits are the binary value prescaler value PRS. The ATD conversion clock frequency is calculated as follows: $\mathrm{ATDclock} = \frac{[\mathrm{BusClock}]}{[\mathrm{PRS}+1]} \times 0.5$ **Note:** The maximum ATD conversion clock frequency is half the Bus Clock. The default (after reset) prescaler value is 5 which results in a default ATD conversion clock frequency that is Bus Clock divided by 12. Table 8-8 illustrates the divide-by operation and the appropriate range of the Bus Clock.

Table 8-7. Sample Time Select

SMP1	SMP0	Length of 2nd Phase of Sample Time
0	0	2 A/D conversion clock periods
0	1	4 A/D conversion clock periods
1	0	8 A/D conversion clock periods
1	1	16 A/D conversion clock periods

Table 9-6. RTICTL Field Descriptions

Field	Description
6:4 RTR[6:4]	**Real-Time Interrupt Prescale Rate Select Bits** — These bits select the prescale rate for the RTI. See Table 9-7.
3:0 RTR[3:0]	**Real-Time Interrupt Modulus Counter Select Bits** — These bits select the modulus counter target value to provide additional granularity. Table 9-7 shows all possible divide values selectable by the RTICTL register. The source clock for the RTI is OSCCLK.

Table 9-7. RTI Frequency Divide Rates

RTR[3:0]	RTR[6:4] =							
	000 (OFF)	**001 (2^{10})**	**010 (2^{11})**	**011 (2^{12})**	**100 (2^{13})**	**101 (2^{14})**	**110 (2^{15})**	**111 (2^{16})**
0000 (÷1)	OFF*	2^{10}	2^{11}	2^{12}	2^{13}	2^{14}	2^{15}	2^{16}
0001 (÷2)	OFF*	$2x2^{10}$	$2x2^{11}$	$2x2^{12}$	$2x2^{13}$	$2x2^{14}$	$2x2^{15}$	$2x2^{16}$
0010 (÷3)	OFF*	$3x2^{10}$	$3x2^{11}$	$3x2^{12}$	$3x2^{13}$	$3x2^{14}$	$3x2^{15}$	$3x2^{16}$
0011 (÷4)	OFF*	$4x2^{10}$	$4x2^{11}$	$4x2^{12}$	$4x2^{13}$	$4x2^{14}$	$4x2^{15}$	$4x2^{16}$
0100 (÷5)	OFF*	$5x2^{10}$	$5x2^{11}$	$5x2^{12}$	$5x2^{13}$	$5x2^{14}$	$5x2^{15}$	$5x2^{16}$
0101 (÷6)	OFF*	$6x2^{10}$	$6x2^{11}$	$6x2^{12}$	$6x2^{13}$	$6x2^{14}$	$6x2^{15}$	$6x2^{16}$
0110 (÷7)	OFF*	$7x2^{10}$	$7x2^{11}$	$7x2^{12}$	$7x2^{13}$	$7x2^{14}$	$7x2^{15}$	$7x2^{16}$
0111 (÷8)	OFF*	$8x2^{10}$	$8x2^{11}$	$8x2^{12}$	$8x2^{13}$	$8x2^{14}$	$8x2^{15}$	$8x2^{16}$
1000 (÷9)	OFF*	$9x2^{10}$	$9x2^{11}$	$9x2^{12}$	$9x2^{13}$	$9x2^{14}$	$9x2^{15}$	$9x2^{16}$
1001 (÷10)	OFF*	$10x2^{10}$	$10x2^{11}$	$10x2^{12}$	$10x2^{13}$	$10x2^{14}$	$10x2^{15}$	$10x2^{16}$
1010 (÷11)	OFF*	$11x2^{10}$	$11x2^{11}$	$11x2^{12}$	$11x2^{13}$	$11x2^{14}$	$11x2^{15}$	$11x2^{16}$
1011 (÷12)	OFF*	$12x2^{10}$	$12x2^{11}$	$12x2^{12}$	$12x2^{13}$	$12x2^{14}$	$12x2^{15}$	$12x2^{16}$
1100 (÷ 13)	OFF*	$13x2^{10}$	$13x2^{11}$	$13x2^{12}$	$13x2^{13}$	$13x2^{14}$	$13x2^{15}$	$13x2^{16}$
1101 (÷14)	OFF*	$14x2^{10}$	$14x2^{11}$	$14x2^{12}$	$14x2^{13}$	$14x2^{14}$	$14x2^{15}$	$14x2^{16}$
1110 (÷15)	OFF*	$15x2^{10}$	$15x2^{11}$	$15x2^{12}$	$15x2^{13}$	$15x2^{14}$	$15x2^{15}$	$15x2^{16}$
1111 (÷ 16)	OFF*	$16x2^{10}$	$16x2^{11}$	$16x2^{12}$	$16x2^{13}$	$16x2^{14}$	$16x2^{15}$	$16x2^{16}$

* Denotes the default value out of reset.This value should be used to disable the RTI to ensure future backwards compatibility.

There are five different scenarios for the CRG to restart the MCU from wait mode:

- External reset
- Clock monitor reset
- COP reset
- Self-clock mode interrupt
- Real-time interrupt (RTI)

If the MCU gets an external reset during wait mode active, the CRG asynchronously restores all configuration bits in the register space to its default settings and starts the reset generator. After completing the reset sequence processing begins by fetching the normal reset vector. Wait mode is exited and the MCU is in run mode again.

If the clock monitor is enabled (CME=1) the MCU is able to leave wait mode when loss of oscillator/external clock is detected by a clock monitor fail. If the SCME bit is not asserted the CRG generates a clock monitor fail reset (CMRESET). The CRG's behavior for CMRESET is the same compared to external reset, but another reset vector is fetched after completion of the reset sequence. If the SCME bit is asserted the CRG generates a SCM interrupt if enabled (SCMIE=1). After generating the interrupt the CRG enters self-clock mode and starts the clock quality checker (see Section 9.4.4, "Clock Quality Checker"). Then the MCU continues with normal operation.If the SCM interrupt is blocked by SCMIE = 0, the SCMIF flag will be asserted and clock quality checks will be performed but the MCU will not wake-up from wait mode.

If any other interrupt source (e.g. RTI) triggers exit from wait mode the MCU immediately continues with normal operation. If the PLL has been powered-down during wait mode the PLLSEL bit is cleared and the MCU runs on OSCCLK after leaving wait mode. The software must manually set the PLLSEL bit again, in order to switch system and core clocks to the PLLCLK.

If wait mode is entered from self-clock mode, the CRG will continue to check the clock quality until clock check is successful. The PLL and voltage regulator (VREG) will remain enabled.

Table 9-11 summarizes the outcome of a clock loss while in wait mode.

Register Name		Bit 7	6	5	4	3	2	1	Bit0
0x00X0 IDR0	R W	ID28	ID27	ID26	ID25	ID24	ID23	ID22	ID21
0x00X1 IDR1	R W	ID20	ID19	ID18	SRR (=1)	IDE (=1)	ID17	ID16	ID15
0x00X2 IDR2	R W	ID14	ID13	ID12	ID11	ID10	ID9	ID8	ID7
0x00X3 IDR3	R W	ID6	ID5	ID4	ID3	ID2	ID1	ID0	RTR
0x00X4 DSR0	R W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0x00X5 DSR1	R W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0x00X6 DSR2	R W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0x00X7 DSR3	R W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0x00X8 DSR4	R W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0x00X9 DSR5	R W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0x00XA DSR6	R W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0x00XB DSR7	R W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0x00XC DLR	R W					DLC3	DLC2	DLC1	DLC0

= Unused, always read 'x'

Figure 10-23. Receive/Transmit Message Buffer — Extended Identifier Mapping

Read: For transmit buffers, anytime when TXEx flag is set (see Section 10.3.2.7, "MSCAN Transmitter Flag Register (CANTFLG)") and the corresponding transmit buffer is selected in CANTBSEL (see Section 10.3.2.11, "MSCAN Transmit Buffer Selection Register (CANTBSEL)"). For receive buffers, only when RXF flag is set (see Section 10.3.2.5, "MSCAN Receiver Flag Register (CANRFLG)").

11.3 Memory Map and Register Definition

The CRG contains the registers and associated bits for controlling and monitoring the OSCV2 module.

11.4 Functional Description

The OSCV2 block has two external pins, EXTAL and XTAL. The oscillator input pin, EXTAL, is intended to be connected to either a crystal or an external clock source. The selection of Colpitts oscillator or Pierce oscillator/external clock depends on the XCLKS signal which is sampled during reset. The XTAL pin is an output signal that provides crystal circuit feedback.

A buffered EXTAL signal, OSCCLK, becomes the internal reference clock. To improve noise immunity, the oscillator is powered by the V_{DDPLL} and V_{SSPLL} power supply pins.

The Pierce oscillator can be used for higher frequencies compared to the low power Colpitts oscillator.

11.4.1 Amplitude Limitation Control (ALC)

The Colpitts oscillator is equipped with a feedback system which does not waste current by generating harmonics. Its configuration is “Colpitts oscillator with translated ground.” The transconductor used is driven by a current source under the control of a peak detector which will measure the amplitude of the AC signal appearing on EXTAL node in order to implement an amplitude limitation control (ALC) loop. The ALC loop is in charge of reducing the quiescent current in the transconductor as a result of an increase in the oscillation amplitude. The oscillation amplitude can be limited to two values. The normal amplitude which is intended for non power saving modes and a small amplitude which is intended for low power operation modes. Please refer to the CRG block description chapter for the control and assignment of the amplitude value to operation modes.

11.4.2 Clock Monitor (CM)

The clock monitor circuit is based on an internal resistor-capacitor (RC) time delay so that it can operate without any MCU clocks. If no OSCCLK edges are detected within this RC time delay, the clock monitor indicates a failure which asserts self clock mode or generates a system reset depending on the state of SCME bit. If the clock monitor is disabled or the presence of clocks is detected no failure is indicated.The clock monitor function is enabled/disabled by the CME control bit, described in the CRG block description chapter.

11.5 Interrupts

OSCV2 contains a clock monitor, which can trigger an interrupt or reset. The control bits and status bits for the clock monitor are described in the CRG block description chapter.

Table 12-3. PWMPOL Field Descriptions (continued)

Field	Description
3 PPOL3	**Pulse Width Channel 3 Polarity** 0 PWM channel 3 output is low at the beginning of the period, then goes high when the duty count is reached. 1 PWM channel 3 output is high at the beginning of the period, then goes low when the duty count is reached.
2 PPOL2	**Pulse Width Channel 2 Polarity** 0 PWM channel 2 output is low at the beginning of the period, then goes high when the duty count is reached. 1 PWM channel 2 output is high at the beginning of the period, then goes low when the duty count is reached.
1 PPOL1	**Pulse Width Channel 1 Polarity** 0 PWM channel 1 output is low at the beginning of the period, then goes high when the duty count is reached. 1 PWM channel 1 output is high at the beginning of the period, then goes low when the duty count is reached.
0 PPOL0	**Pulse Width Channel 0 Polarity** 0 PWM channel 0 output is low at the beginning of the period, then goes high when the duty count is reached 1 PWM channel 0 output is high at the beginning of the period, then goes low when the duty count is reached.

12.3.2.3 PWM Clock Select Register (PWMCLK)

Each PWM channel has a choice of two clocks to use as the clock source for that channel as described below.

Module Base + 0x0002

	7	6	5	4	3	2	1	0
R	0	0	PCLK5	PCLK4	PCLK3	PCLK2	PCLK1	PCLK0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 12-5. PWM Clock Select Register (PWMCLK)

Read: anytime

Write: anytime

NOTE

Register bits PCLK0 to PCLK5 can be written anytime. If a clock select is changed while a PWM signal is being generated, a truncated or stretched pulse can occur during the transition.

NOTE

Reads of this register return the most recent value written. Reads do not necessarily return the value of the currently active duty due to the double buffering scheme.

Reference Section 12.4.2.3, “PWM Period and Duty,” for more information.

NOTE

Depending on the polarity bit, the duty registers will contain the count of either the high time or the low time. If the polarity bit is 1, the output starts high and then goes low when the duty count is reached, so the duty registers contain a count of the high time. If the polarity bit is 0, the output starts low and then goes high when the duty count is reached, so the duty registers contain a count of the low time.

To calculate the output duty cycle (high time as a % of period) for a particular channel:

- Polarity = 0 (PPOLx = 0)
  Duty cycle = [(PWMPERx PWMDTYx)/PWMPERx] * 100%
- Polarity = 1 (PPOLx = 1)
  Duty cycle = [PWMDTYx / PWMPERx] * 100%
- For boundary case programming values, please refer to Section 12.4.2.8, “PWM Boundary Cases.”

Module Base + 0x0018

	7	6	5	4	3	2	1	0
R W	Bit 7	6	5	4	3	2	1	Bit 0
Reset	1	1	1	1	1	1	1	1

Figure 12-27. PWM Channel Duty Registers (PWMDTY0)

Module Base + 0x0019

	7	6	5	4	3	2	1	0
R W	Bit 7	6	5	4	3	2	1	Bit 0
Reset	1	1	1	1	1	1	1	1

Figure 12-28. PWM Channel Duty Registers (PWMDTY1)

Module Base + 0x001A

	7	6	5	4	3	2	1	0
R W	Bit 7	6	5	4	3	2	1	Bit 0
Reset	1	1	1	1	1	1	1	1

Figure 12-29. PWM Channel Duty Registers (PWMDTY2)

Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x000D TSCR2	R	TOI	0	0	0	TCRE	PR2	PR1	PR0
	W								
0x000E TFLG1	R	C7F	C6F	C5F	C4F	C3F	C2F	C1F	C0F
	W								
0x000F TFLG2	R	TOF	0	0	0	0	0	0	0
	W								
0x0010–0x001F TCxH–TCxL	R	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
	W								
	R	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	W								
0x0020 PACTL	R	0	PAEN	PAMOD	PEDGE	CLK1	CLK0	PAOVI	PAI
	W								
0x0021 PAFLG	R	0	0	0	0	0	0	PAOVF	PAIF
	W								
0x0022 PACNTH	R	PACNT15	PACNT14	PACNT13	PACNT12	PACNT11	PACNT10	PACNT9	PACNT8
	W								
0x0023 PACNTL	R	PACNT7	PACNT6	PACNT5	PACNT4	PACNT3	PACNT2	PACNT1	PACNT0
	W								
0x0024–0x002F Reserved	R								
	W								

= Unimplemented or Reserved

Figure 15-5. TIM16B8CV1 Register Summary (continued)

15.3.2.1 Timer Input Capture/Output Compare Select (TIOS)

Module Base + 0x0000

	7	6	5	4	3	2	1	0
R/W	IOS7	IOS6	IOS5	IOS4	IOS3	IOS2	IOS1	IOS0
Reset	0	0	0	0	0	0	0	0

Figure 15-6. Timer Input Capture/Output Compare Select (TIOS)

Read: Anytime

19.4.1.3 Valid Flash Commands

Table 19-17 summarizes the valid Flash commands along with the effects of the commands on the Flash array.

Table 19-17. Valid Flash Commands

FCMD	Meaning	Function on Flash Array
0x05	Erase Verify	Verify all bytes in the Flash array are erased. If the Flash array is erased, the BLANK bit will set in the FSTAT register upon command completion.
0x20	Program	Program a word (2 bytes) in the Flash array.
0x40	Sector Erase	Erase all 1024 bytes in a sector of the Flash array.
0x41	Mass Erase	Erase all bytes in the Flash array. A mass erase of the full Flash array is only possible when FPLDIS, FPHDIS, and FPOPEN bits in the FPROT register are set prior to launching the command.

CAUTION

A Flash word must be in the erased state before being programmed. Cumulative programming of bits within a Flash word is not allowed.

19.4.2 Operating Modes

19.4.2.1 Wait Mode

If the MCU enters wait mode while a Flash command is active (CCIF = 0), that command and any buffered command will be completed.

The Flash module can recover the MCU from wait mode if the interrupts are enabled (see Section 19.4.5).

19.4.2.2 Stop Mode

If the MCU enters stop mode while a Flash command is active (CCIF = 0), that command will be aborted and the data being programmed or erased is lost. The high voltage circuitry to the Flash array will be switched off when entering stop mode. CCIF and ACCERR flags will be set. Upon exit from stop mode, the CBEIF flag will be set and any buffered command will not be executed. The ACCERR flag must be cleared before returning to normal operation.

NOTE

As active Flash commands are immediately aborted when the MCU enters stop mode, it is strongly recommended that the user does not use the STOP instruction during program and erase execution.

19.4.2.3 Background Debug Mode

In background debug mode (BDM), the FPROT register is writable. If the MCU is unsecured, then all Flash commands listed in Table 19-17 can be executed. If the MCU is secured and is in special single chip mode, the only possible command to execute is mass erase.

19.4.3 Flash Module Security

The Flash module provides the necessary security information to the MCU. After each reset, the Flash module determines the security state of the MCU as defined in Section 19.3.2.2, “Flash Security Register (FSEC)”.

The contents of the Flash security/options byte at address 0xFF0F in the Flash configuration field must be changed directly by programming address 0xFF0F when the device is unsecured and the higher address sector is unprotected. If the Flash security/options byte is left in the secure state, any reset will cause the MCU to return to the secure operating mode.

19.4.3.1 Unsecuring the MCU using Backdoor Key Access

The MCU may only be unsecured by using the backdoor key access feature which requires knowledge of the contents of the backdoor key (four 16-bit words programmed at addresses 0xFF00–0xFF07). If KEYEN[1:0] = 1:0 and the KEYACC bit is set, a write to a backdoor key address in the Flash array triggers a comparison between the written data and the backdoor key data stored in the Flash array. If all four words of data are written to the correct addresses in the correct order and the data matches the backdoor key stored in the Flash array, the MCU will be unsecured. The data must be written to the backdoor key

Chapter 20
96 Kbyte Flash Module (S12FTS96KV1)

20.1 Introduction

The FTS128K1FTS96K module implements a 12896 Kbyte Flash (nonvolatile) memory. The Flash memory contains one array of 12896 Kbytes organized as 1024768 rows of 128128 bytes with an erase sector size of eight rows (10241024 bytes). The Flash array may be read as either bytes, aligned words, or misaligned words. Read access time is one bus cycle for byte and aligned word, and two bus cycles for misaligned words.

The Flash array is ideal for program and data storage for single-supply applications allowing for field reprogramming without requiring external voltage sources for program or erase. Program and erase functions are controlled by a command driven interface. The Flash module supports both mass erase and sector erase. An erased bit reads 1 and a programmed bit reads 0. The high voltage required to program and erase is generated internally. It is not possible to read from a Flash array while it is being erased or programmed.

CAUTION

A Flash word must be in the erased state before being programmed. Cumulative programming of bits within a Flash word is not allowed.

20.1.1 Glossary

Command Write Sequence — A three-step MCU instruction sequence to program, erase, or erase verify the Flash array memory.

20.1.2 Features

- 12896 Kbytes of Flash memory comprised of one 12896 Kbyte array divided into 12896 sectors of 10241024 bytes
- Automated program and erase algorithm
- Interrupts on Flash command completion and command buffer empty
- Fast sector erase and word program operation
- 2-stage command pipeline for faster multi-word program times
- Flexible protection scheme to prevent accidental program or erase
- Single power supply for Flash program and erase operations
- Security feature to prevent unauthorized access to the Flash array memory

20.4.2 Operating Modes

20.4.2.1 Wait Mode

If the MCU enters wait mode while a Flash command is active (CCIF = 0), that command and any buffered command will be completed.

The Flash module can recover the MCU from wait mode if the interrupts are enabled (see Section 20.4.5).

20.4.2.2 Stop Mode

If the MCU enters stop mode while a Flash command is active (CCIF = 0), that command will be aborted and the data being programmed or erased is lost. The high voltage circuitry to the Flash array will be switched off when entering stop mode. CCIF and ACCERR flags will be set. Upon exit from stop mode, the CBEIF flag will be set and any buffered command will not be executed. The ACCERR flag must be cleared before returning to normal operation.

NOTE

As active Flash commands are immediately aborted when the MCU enters stop mode, it is strongly recommended that the user does not use the STOP instruction during program and erase execution.

20.4.2.3 Background Debug Mode

In background debug mode (BDM), the FPROT register is writable. If the MCU is unsecured, then all Flash commands listed in Table 20-17 can be executed. If the MCU is secured and is in special single chip mode, the only possible command to execute is mass erase.

20.4.3 Flash Module Security

The Flash module provides the necessary security information to the MCU. After each reset, the Flash module determines the security state of the MCU as defined in Section 20.3.2.2, "Flash Security Register (FSEC)".

The contents of the Flash security/options byte at address 0xFF0F in the Flash configuration field must be changed directly by programming address 0xFF0F when the device is unsecured and the higher address sector is unprotected. If the Flash security/options byte is left in the secure state, any reset will cause the MCU to return to the secure operating mode.

20.4.3.1 Unsecuring the MCU using Backdoor Key Access

The MCU may only be unsecured by using the backdoor key access feature which requires knowledge of the contents of the backdoor key (four 16-bit words programmed at addresses 0xFF00–0xFF07). If KEYEN[1:0] = 1:0 and the KEYACC bit is set, a write to a backdoor key address in the Flash array triggers a comparison between the written data and the backdoor key data stored in the Flash array. If all four words of data are written to the correct addresses in the correct order and the data matches the backdoor key stored in the Flash array, the MCU will be unsecured. The data must be written to the backdoor key

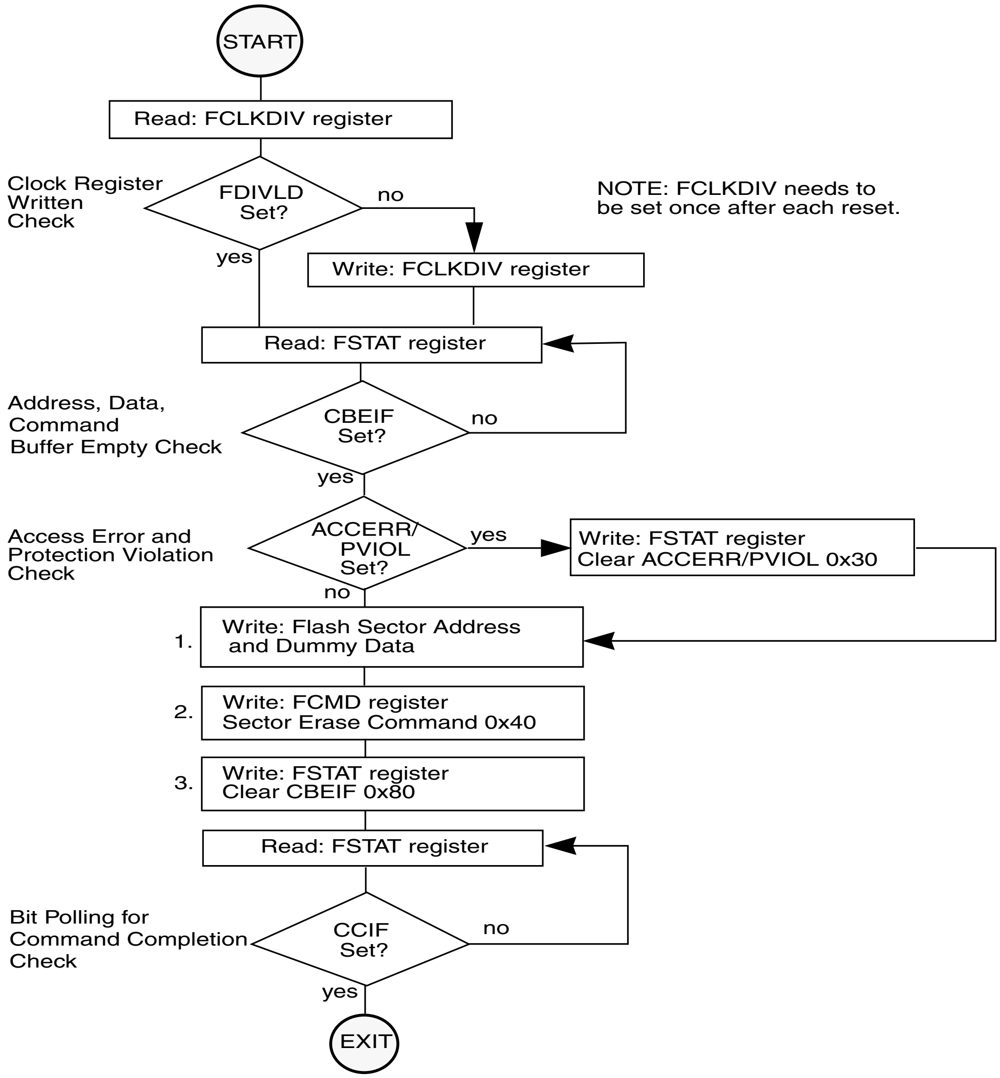

Figure 21-24. Example Sector Erase Command Flow

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